SN74AUP1T34-Q1 1 位单向电压电平转换器

1 特性

- 适用于汽车电子 应用
  - 符合 AEC-Q100 标准
  - 器件温度等级 1：-40°C 至 125°C 的环境运行温度范围
  - 器件人体放电模式 (HBM) 静电放电 (ESD) 分类等级 3A
  - 带电器件模型 (CDM) ESD 分类等级 C5
- 0.9V 至 3.6V 的宽运行 VCC 范围
- 均衡的传播延迟：$t_{PLH} = t_{PHL}$（1.8V 至 3.3V 转换时的典型值）
- 低静态功耗：ICC 最高为 5μA
- ±6mA 输出驱动（电压为 3V 时）
- I_{off} 支持部分掉电模式运行
- VCC 隔离特性 – 如果 V_{CCA} 输入接地，则 B 端口处于高阻态
- 输入滞后可实现输入转换和输入上更好的开关噪声抗扰度
- 静电放电 (ESD) 保护性能超过 JESD 22 规范要求
- 5000V 人体模型 (AEC-Q100-002-E)
- 锁存性能满足 100mA，符合 Q100-004-D 规范

2 应用范围

- 汽车
- 企业
- 工业
- 个人电子产品
- 电信

3 说明

SN74AUP1T34-Q1 器件是一款 1 位非反向转换器，使用两条独立的可配置电源轨。该单向转换器在 A 和 B 两端口间转换。A 端口设计用于跟踪 V_{CCA}。V_{CCA}可接受从 0.9V 到 3.6V 范围内的电源电压。B 端口设计用于跟踪 V_{CCB}。V_{CCB}可接受从 0.9V 至 3.6V 间的电源电压值。这可实现 1V，1.2V，1.5V，1.8V，2.5V 和 3.3V 电压节点间的低压转换。此外，SN74AUP1T34-Q1 完全 适用于 使用 I_{off} 的局部掉电应用。I_{off} 电路会禁用输出，从而在器件掉电时防止电流回流损坏器件。

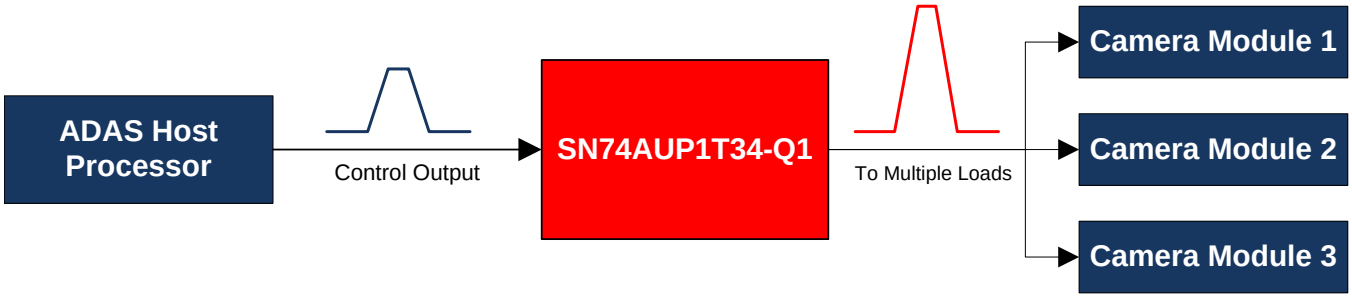
VCC 隔离特性确保了在 V_{CCA}输入在 GND 上时，B 端口处于高阻抗状态。如果 V_{CCB}输入在 GND 上，到 A 侧的任一输入都不会导致泄漏电流，即使在悬空状态时也是如此。

器件信息(1)

器件型号	封装	封装尺寸（标称值）
SN74AUP1T34-Q1	SC70 (5)	2.00mm × 1.25mm

(1) 要了解所有可用封装，请参见数据表末尾的可订购产品附录。

示例应用图



目录

4 修订历史记录

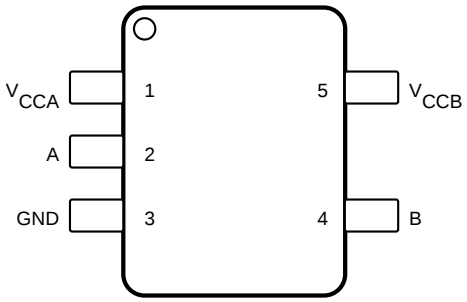
注：之前版本的页码可能与当前版本有所不同。

Changes from Original (December 2013) to Revision A **Page**

- 已添加 *ESD 额定值*表，*特性* *描述*部分，*器件功能模式*，*应用和实施*部分，*电源相关建议*部分，*布局*部分，*器件和文档支持*部分以及*机械、封装和可订购信息*部分。 ... 1
- 已删除*订购信息表* ... 1

5 Pin Configuration and Functions

DCK Package
5-Pin SC70
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A	2	I	Input Port. Referenced to V_{CCA}.
B	4	O	Output Port. Referenced to V_{CCB}.
GND	3	—	Ground.
V_{CCA}	1	—	Input Port DC Power Supply.
V_{CCB}	5	—	Output Port DC Power Supply.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CCA}, V_{CCB}	Supply voltage		–0.3	4	V
V_I	Input voltage		–0.5	4.6	V
V_O	Voltage applied to any output in the high-impedance or power-off state		–0.5	4.6	V
	Voltage applied to any output in the high or low state		–0.5	4.6	
I_{IK}	Input clamp current	$V_I < 0$		–50	mA
I_{OK}	Output clamp current	$V_O < 0$		–50	mA
I_O	Continuous output current			±50	mA
	Continuous current through VCCA or GND			±100	mA
T_{stg}	Storage temperature		–65	150	°C

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1), Classification 3A	5000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2), Classification C5	750	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		VCCA	VCCB	MIN	MAX	UNIT
V_{CCA}, V_{CCB}	Supply voltage					0.9	3.6	V
V_{IH}	High-level input voltage			0.9 V to 1.95 V	0.9 V to 1.95 V	0.65 × V_{CCA}		V
				2.3 V to 2.7 V	0.9 V to 3.6 V	1.6		
				3 V to 3.6 V	0.9 V to 3.6 V	2		
V_{IL}	Low-level input voltage			0.9 V	0.9 V to 1.95 V		0.3 × V_{CCA}	V
				1 V to 1.95 V	0.9 V to 1.95 V		0.35 × V_{CCA}	
				2.3 V to 2.7 V	0.9 V to 3.6 V		0.7	
				3 V to 3.6 V	0.9 V to 3.6 V		0.9	
Δt/Δv	Input transition rise or fall rate			3 V to 3.6 V	0.9 V to 3.6 V		200	ns/V
T_A	Operating free-air temperature					–40	125	°C
V_{OH}		I_{OH} = –100 µA	V_I = V_{IH}	0.9 V to 3.6 V	0.9 V to 3.6 V	VCCB – 0.2		V
		I_{OH} = –0.25 mA		0.9 V to 1 V	0.9 V to 1 V	0.75 × VCCB		
		I_{OH} = –1.5 mA		1.2 V	1.2 V	1		
		I_{OH} = –2 mA		1.65 V	1.65 V	1.32		
		I_{OH} = –3 mA		2.3 V	2.3 V	1.9		
		I_{OH} = –6 mA		3 V	3 V	2.72		
V_{OL}		I_{OL} = 100 µA	V_I = V_{IL}	0.9 V to 3.6 V	0.9 V to 3.6 V		0.1	V
		I_{OL} = 0.25 mA		0.9 V to 1 V	0.9 V 1 V		0.1	
		I_{OL} = 1.5 mA		1.2 V	1.2 V		0.3 × VCCB	
		I_{OL} = 2 mA		1.65 V	1.65 V		0.31	
		I_{OL} = 3 mA		2.3 V	2.3 V		0.31	
		I_{OL} = 6 mA		3 V	3 V		0.31	
I_I	Control inputs	V_I = VCCA or GND		0.9 V to 3.6 V	0.9 V to 3.6 V		±1	µA
I_{off}	A or B port	VI or VO = 0 to 3.6 V		0 V	0 V to 3.6 V		±5	µA
				0 V to 3.6 V	0 V		±5	
I_{CCA}		VI = VCCI or GND, IO = 0 mA		0.9 V to 3.6 V	0.9 V to 3.6 V		2.7	µA
				0.9 V to 3.6 V	VCCA		2	
				0 V	0 V to 3.6 V		1	
				0 V to 3.6 V	0 V		1	
I_{CCB}		VI = VCCI or GND, IO = 0 mA		0.9 V to 3.6 V	0.9 V to 3.6 V		2.7	µA
				0.9 V to 3.6 V	VCCA		2	
				0 V	0 V to 3.6 V		1	
				0 V to 3.6 V	0 V		1	
I_{CCA} + I_{CCB}		VI = VCCI or GND, IO = 0 mA		0.9 V to 3.6 V	0.9 V to 3.6 V		5.4	µA
C_{io}	A or B port			3.3 V	3.3 V		4	pF

6.4 Thermal Information

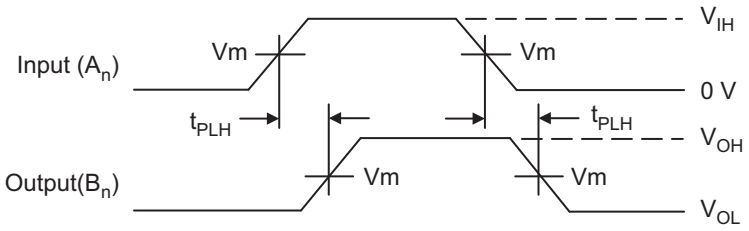
THERMAL METRIC[1]		SN74AUP1T34-Q1 DCK (SC70) 5 PINS	UNIT
$R_{θJA}$	Junction-to-ambient thermal resistance	301.9	°C/W
$R_{θJC(top)}$	Junction-to-case (top) thermal resistance	113	°C/W
$R_{θJB}$	Junction-to-board thermal resistance	79.1	°C/W
$ψ_{JT}$	Junction-to-top characterization parameter	3.9	°C/W
$ψ_{JB}$	Junction-to-board characterization parameter	78.3	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 AC Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER	C_L	VCCA	VCCB = 0.9 V		VCCB = 1.2 V		VCCB = 1.65 V		VCCB = 2.3 V		VCCB = 3 V		UNIT
			TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	TYP	MAX	
t_{PLH}/t_{PHL}	5 pF	0.9 V	25		18		16.2		16.3		16.8		ns
	5 pF	1.2 V		42.5		24.9		23.2		22.6		22.5	
	5 pF	1.65 V		40		10.7		8.84		8.08		7.88	
	5 pF	2.3 V		41.3		8.02		5.73		4.92		4.2	
	5 pF	3 V		42.5		7.61		4.5		3.65		3.39	
t_{PLH}/t_{PHL}	10 pF	0.9 V	28.9		19.8		17.9		18		18.5		ns
	10 pF	1.2 V		43.22		12.33		9.57		8.81		8.61	
	10 pF	1.65 V		40.44		9.21		6.57		5.6		4.73	
	10 pF	2.3 V		41.56		8.3		5.54		4.42		4.07	
	10 pF	3 V		42.81		7.87		4.8		3.8		3.36	
t_{PLH}/t_{PHL}	15 pF	0.9 V	30.6		21.6		19.6		19.7		20.3		ns
	15 pF	1.2 V		43.87		16.2		11.8		11		11	
	15 pF	1.65 V		40.78		14.7		8.8		7.1		6.4	
	15 pF	2.3 V		41.79		14.9		7.6		5.88		5.27	
	15 pF	3 V		43.09		16.2		6.98		5.4		4.7	
t_{PLH}/t_{PHL}	30 pF	0.9 V	32.1		21.3		18.7		18		18.3		ns
	30 pF	1.2 V		45.65		15.1		12.37		11.61		11.41	
	30 pF	1.65 V		41.72		12.18		8.15		6.94		6.1	
	30 pF	2.3 V		42.44		12.35		7.25		5.55		4.97	
	30 pF	3 V		43.69		11.6		6.92		4.95		4.35	



$V_{MI} = V_{IH}/2$; $V_{MO} = V_{CCB}/2$

$t_R = t_F$ = 2.0 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 1. Waveform 1 - Propagation Delays

6.6 Typical Characteristics

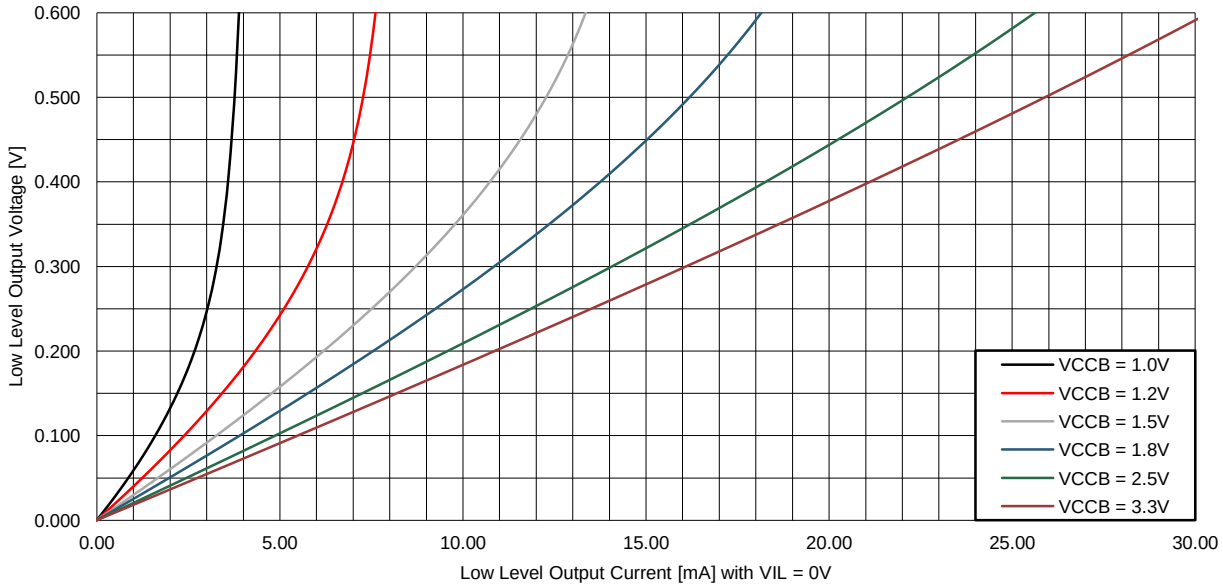
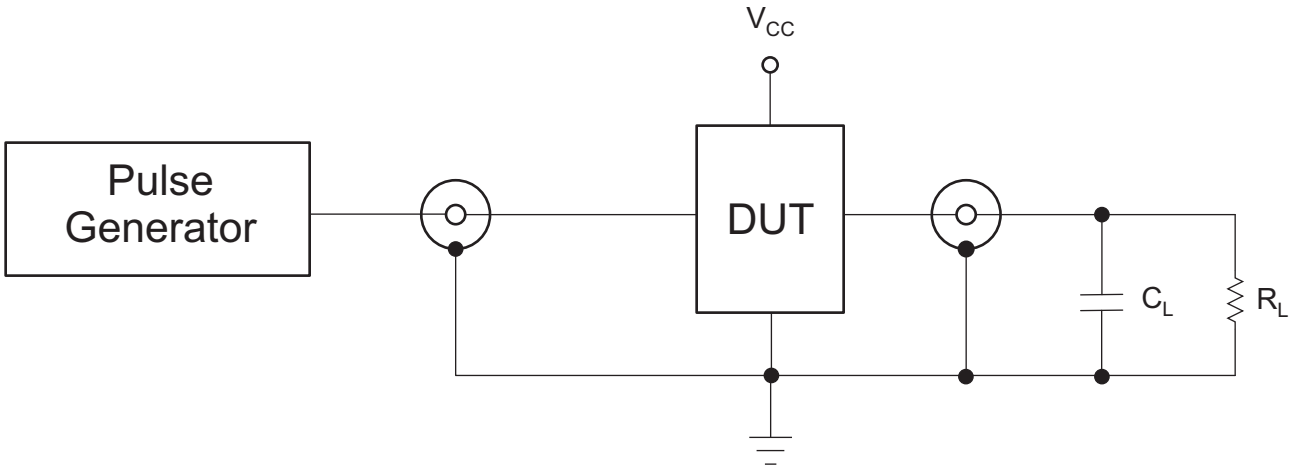


Figure 2. Low Level Output Voltage vs Low Level Output Current

7 Parameter Measurement Information



TEST

t_{PLH}, t_{PHL}

C_L = 5 pF, 10 pF, 15 pF, 30 pF or equivalent (includes probe and jig capacitance)
R_L = 1 MΩ or equivalent
Z_{OUT} of pulse generator = 50 Ω

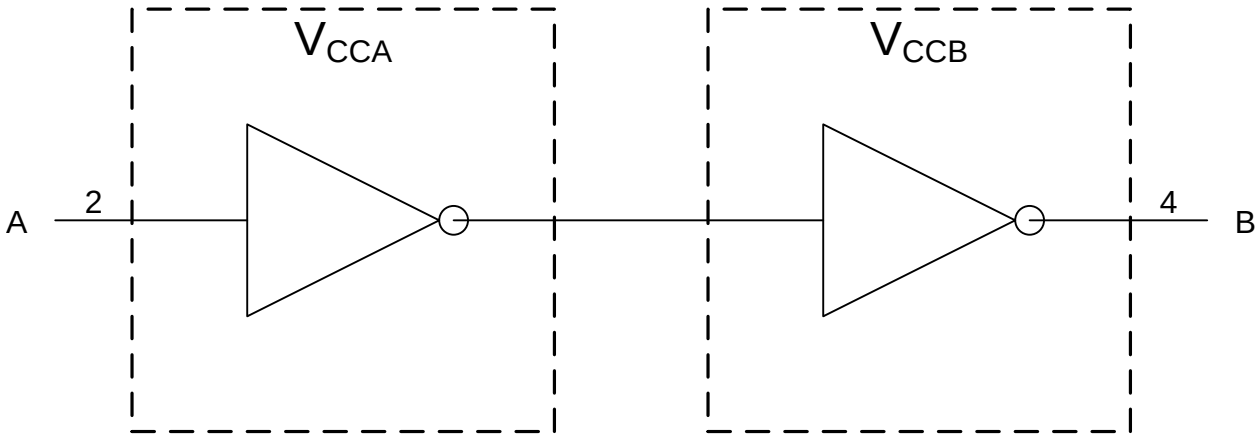
Figure 3. AC (Propagation Delay) Test Circuit

8 Detailed Description

8.1 Overview

The SN74AUP1T34-Q1 is a unidirectional, single-bit, dual-supply, noninverting voltage-level translator. Pin A, which is referenced to V_{CCA}, receives the signal that is to be level translated. Pin B, which is referenced to V_{CCB}, transmits the level translated signal. Both supply pins V_{CCA} and V_{CCB} support a voltage range from 0.9 V to 3.6 V.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Fully Configurable Dual-Rail Design

Both V_{CCA} and V_{CCB} can be supplied at any voltage from 0.9 V to 3.6 V, making the device suitable for translating between any of the voltage nodes (1 V, 1.2 V, 1.8 V, 2.5 V, and 3.3 V).

8.3.2 Partial-Power-Down Mode Operation

I_{off} circuitry disables the outputs, preventing damaging current backflow through the SN74AUP1T34-Q1 when it is powered down. This can occur in applications where subsections of a system are powered down (partial-power-down) to reduce power consumption.

8.3.3 V_{CC} Isolation

The V_{CC} isolation feature ensures that if either V_{CCA} or V_{CCB} are at GND (or < 0.4 V), both ports A and B are set to a high-impedance state, preventing false logic levels from being presented to either bus.

8.3.4 Input Hysteresis

Input hysteresis allows the input to support slew rates as slow as 200 ns/V, improving switching noise immunity.

8.4 Device Functional Modes

Table 1 lists the functional modes of the SN74AUP1T34-Q1.

Table 1. Function Table

INPUT	OUTPUT
A PORT	**B PORT**
L	L
H	H

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74AUP1T34-Q1 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another.

9.2 Typical Application

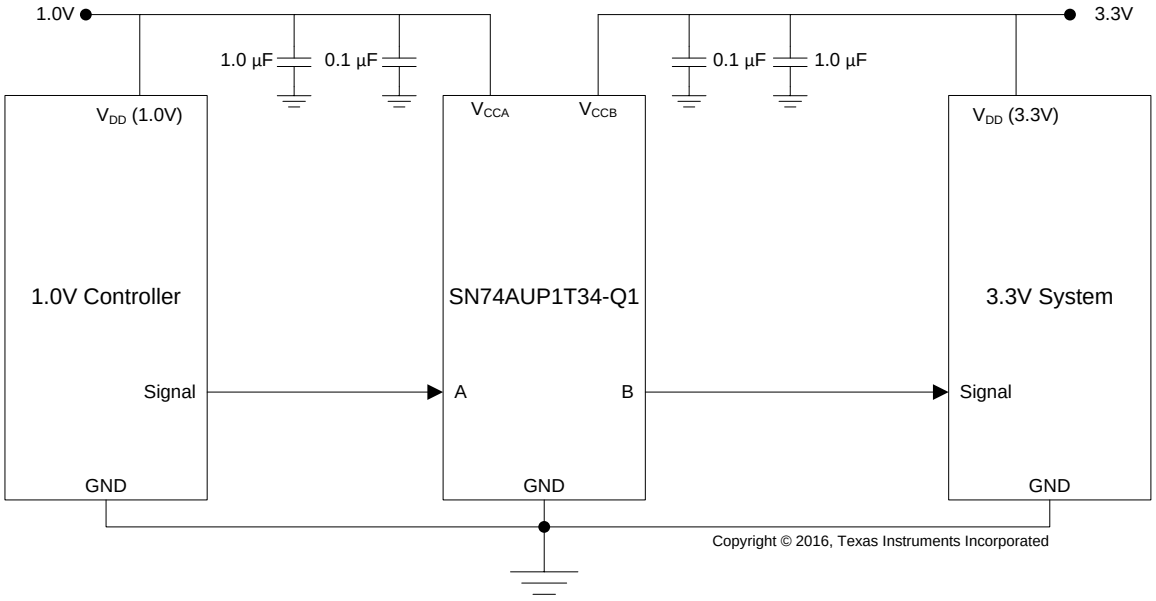


Figure 4. Typical Application Example

9.2.1 Design Requirements

Table 2 lists the design requirements of the SN74AUP1T34-Q1.

Table 2. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input Voltage Range	0.9 V to 3.6 V
Output Voltage Range	0.9 V to 3.6 V

9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
  - Use the supply voltage of the device that is driving the SN74AUP1T34-Q1 device to determine the input voltage range. For a valid logic-high, the value must exceed the V_{IH} of the input port. For a valid logic low the value must be less than the V_{IL} of the input port.
- Output voltage range
  - Use the supply voltage of the device that the SN74AUP1T34-Q1 device is driving to determine the output voltage range.

9.2.3 Application Curve

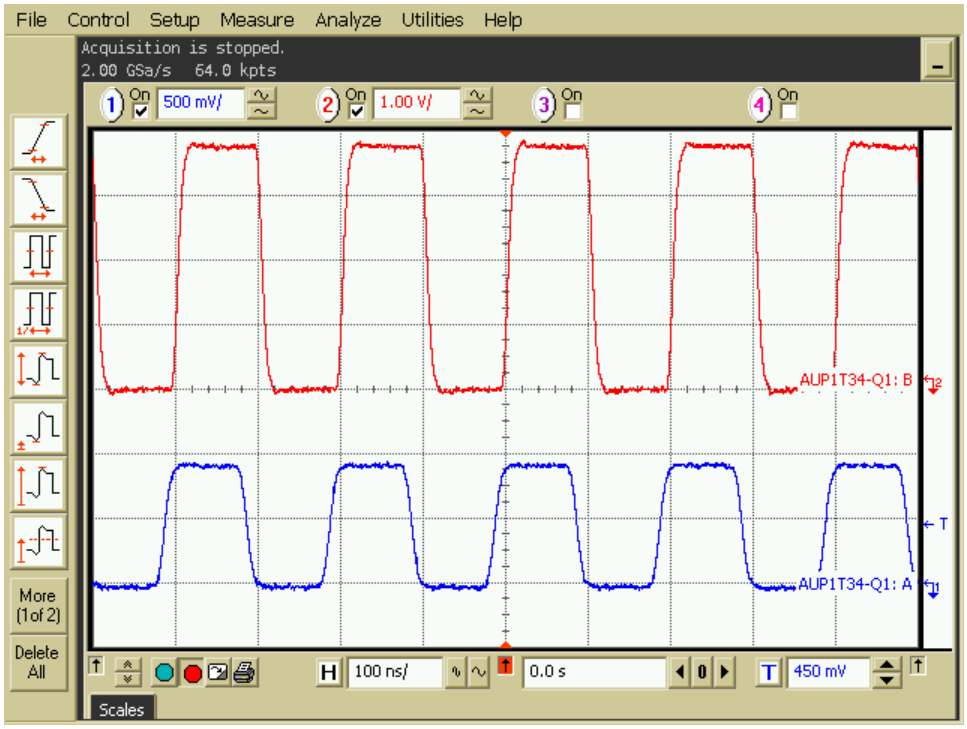


Figure 5. 10 MHz Up Translation (0.9 V to 3.6 V)

10 Power Supply Recommendations

Connect ground before applying either V_{CCA} or V_{CCB}. There is no specific power sequence requirement for the SN74AUP1T34. V_{CCA} or V_{CCB} may be powered up first, and V_{CCA} or V_{CCB} may be powered down first.

11 Layout

11.1 Layout Guidelines

To ensure reliability of the device, TI recommends following common printed-circuit board layout guidelines.

- Bypass capacitors must be used on power supplies.
- Short trace lengths must be used to avoid excessive loading.
- Placing pads on the signal paths for loading capacitors or pullup resistors helps adjust rise and fall times of signals depending on the system requirements.

11.2 Layout Example

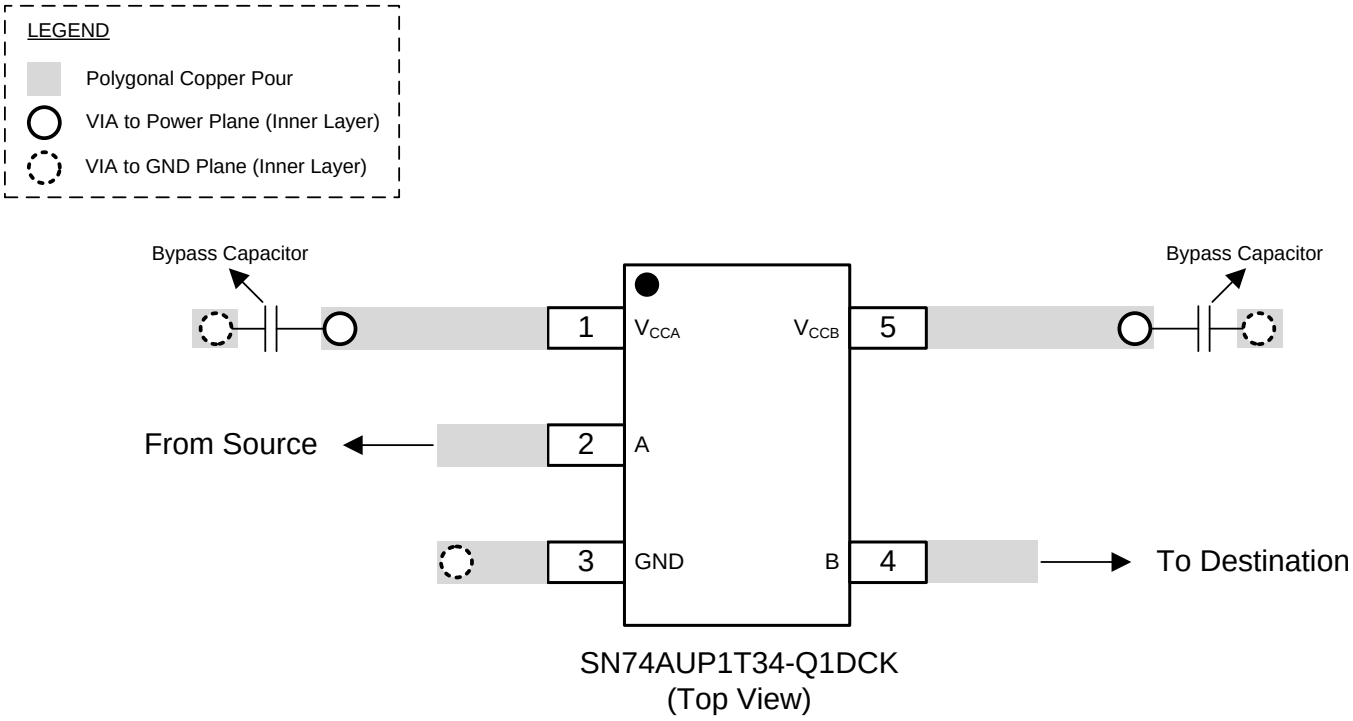


Figure 6. Example Layout

12 器件和文档支持

12.1 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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12.3 静电放电警告

这些装置包含有限的内置 ESD 保护。 存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

12.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

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数据转换器	www.ti.com.cn/dataconverters	消费电子	www.ti.com/consumer-apps
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无线连通性	www.ti.com.cn/wirelessconnectivity	德州仪器在线技术支持社区	www.deyisupport.com

邮寄地址： 上海市浦东新区世纪大道1568 号，中建大厦32 楼邮政编码： 200122

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUP1T34QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	U4E	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN74AUP1T34-Q1 :

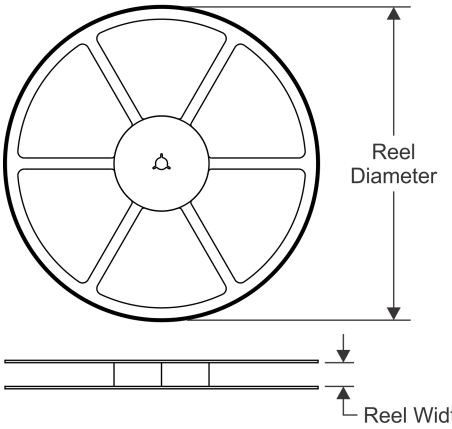
- Catalog: SN74AUP1T34

NOTE: Qualified Version Definitions:

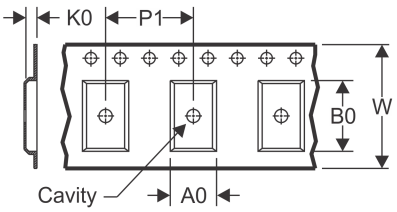
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS

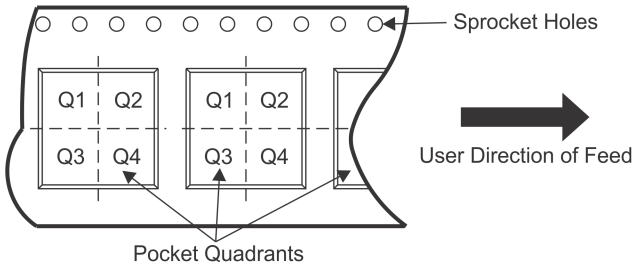


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

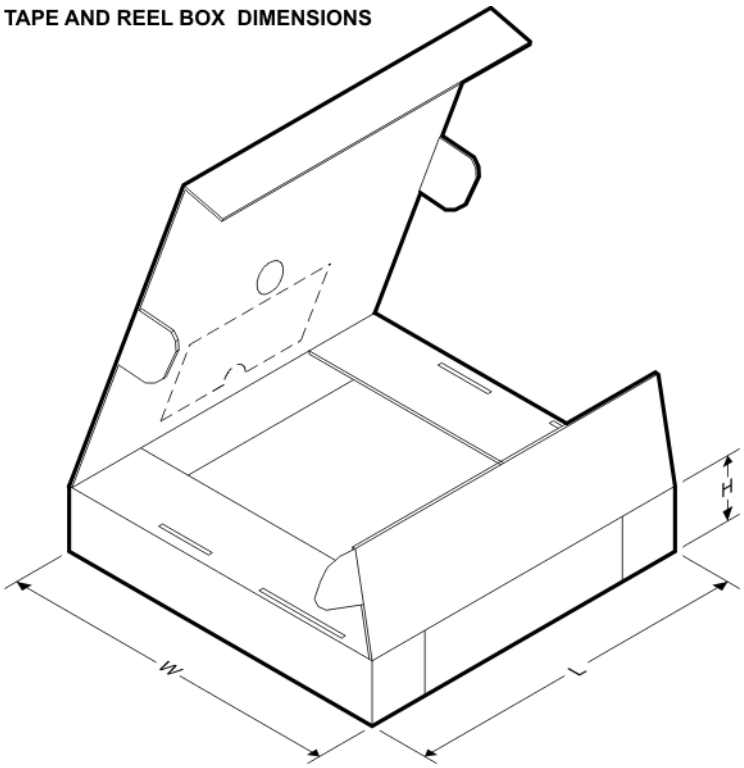
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1T34QDCKRQ1	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

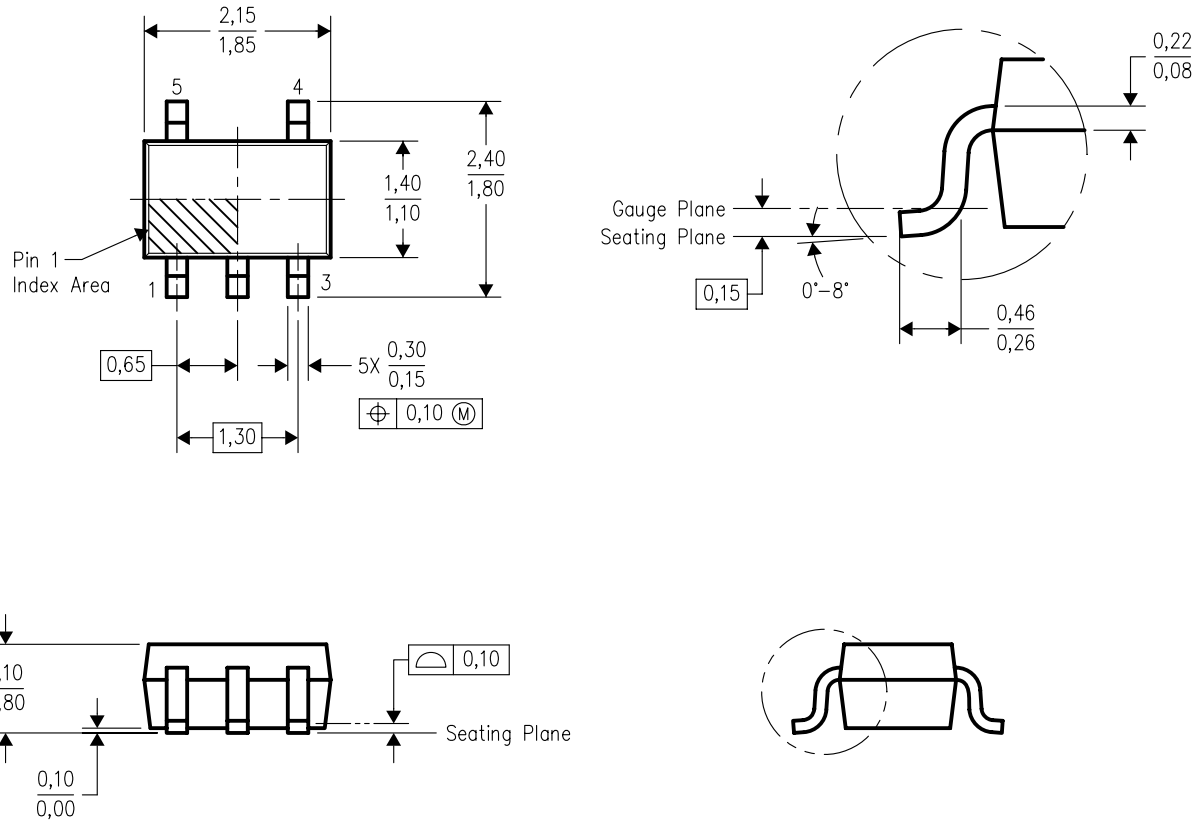
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP1T34QDCKRQ1	SC70	DCK	5	3000	180.0	180.0	18.0

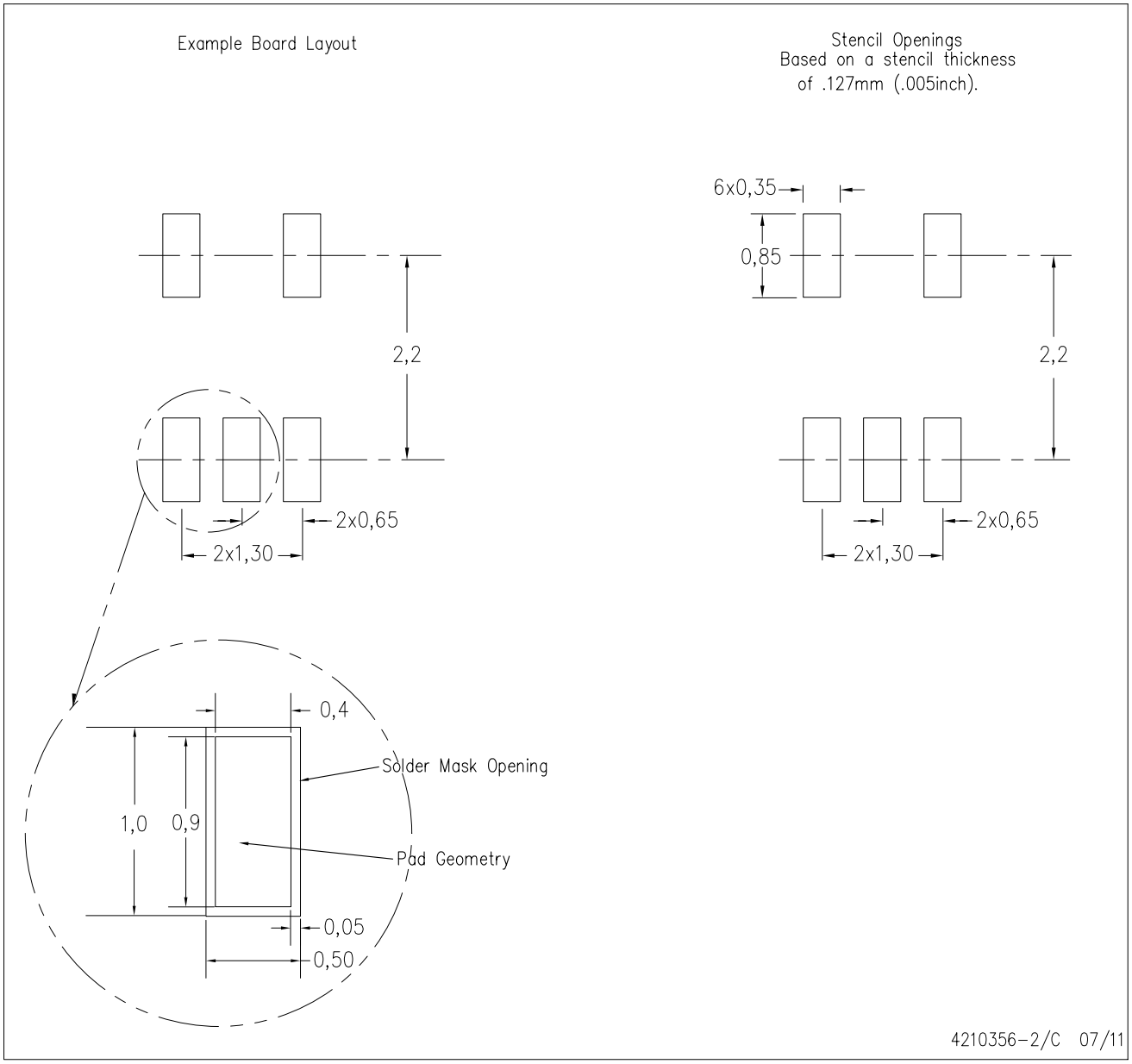
DCK (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4093553–3/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AA.

DCK (R–PDSO–G5) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC–7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC–7525 for other stencil recommendations.

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